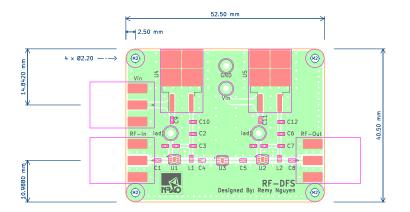
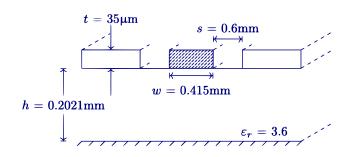
TOP-L1



Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0



BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1.5670 mm

Board overall dimensions: 52.5000 mm x 40.5000 mm

Min track/spacing: 0.415 mm / 0.300 mm Min hole diameter: 0.3000 mm

Copper Finish: ENIG Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Notes: LNA footprint is pin-compatible with PMA2-123LN+.

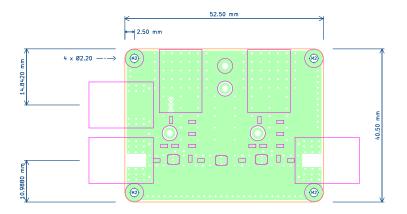
Remy Nguyen

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

Size: A4 Date: 1/23/2024 Rev: c KiCad E.D.A. kicad 7.0.5 ld: 1/1

IN-L2



Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1.5670 mm

Board overall dimensions: 52.5000 mm x 40.5000 mm

Min track/spacing: 0.415 mm / 0.300 mm Min hole diameter: 0.3000 mm

Copper Finish: ENIG Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Notes: LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

Size: A4 Date: 1/23/2024 Rev: c KiCad E.D.A. kicad 7.0.5 ld: 1/1

IN-L3 → 2.50 mm 4 x Ø2.20 →·→ **BOARD CHARACTERISTICS** Copper Layer Count: Board Thickness: 1.5670 mm Layer Name Type Material Thickness (mm) Color Epsilon R Loss Tangent Board overall dimensions: $52.5000 \text{ mm} \times 40.5000 \text{ mm}$ F.Silkscreen Top Silk Screen Liquid Photo 0 mm White Min track/spacing: 0.415 mm / 0.300 mm Min hole diameter: 0.3000 mm F.Paste Top Solder Paste 0 mm Copper Finish: ENIG Impedance Control: Yes F.Mask Top Solder Mask 0.0254 mm 3.3 Liquid Ink Purple 0 Castellated pads: Plated Board Edge: No No F.Cu copper 0.0432 mm 0 Edge card connectors: No FR408HR 2113 0.2021 mm FR4 natural 3.6 0.01 Dielectric 1 prepreq In1.Cu copper 0.0175 mm LNA footprint is pin-compatible with PMA2-123LN+. Dielectric 2 core FR408-HR 0.9906 mm FR4 natural 3.64 0.0098 In2.Cu copper 0.0175 mm 0 Dielectric 3 prepreg FR408HR 2113 0.2021 mm FR4 natural 3.6 0.01

B.Cu

B.Mask

B.Paste

copper

Bottom Solder Mask Liquid Ink

Bottom Solder Paste

B.Silkscreen Bottom Silk Screen Liquid Photo

0.0432 mm

0.0254 mm

0 mm

0 mm

3.3

Purple

White

0

0

Remy Nguyen

Rev: C

ld: 1/1

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Date: 1/23/2024

Title: RF-DFS Gain Circuit

KiCad E.D.A. kicad 7.0.5

Size: A4

BOT-L4

← 2.50 mm 4 x Ø2.20 →·→

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1.5670 mm

Board overall dimensions: 52.5000 mm x 40.5000 mm

Min track/spacing: 0.415 mm / 0.300 mm Min hole diameter: 0.3000 mm

Copper Finish: ENIG Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Notes: LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit				
Size: A4	Date: 1/23/2024	Rev: C		
KiCad E.D.A. kicad 7.0.5 Id: 1/1				